

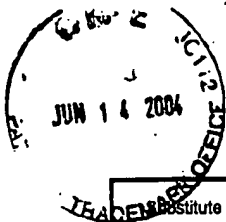
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (use as many sheets as necessary)		<b>Complete if Known</b>			
		Application Number	10/798,731		
		Filing Date	March 10, 2004		
		First Named Inventor	Aoyagi, Seiji		
		Art Unit	Not Yet Assigned		
		Examiner Name	Not Yet Assigned		
Sheet	1	of	1	Attorney Docket Number	020859-002810US

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials *	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
T.B.	2	<a href="http://www.alps.co.jp/e/technology/03/2002/sep/2.htm">http://www.alps.co.jp/e/technology/03/2002/sep/2.htm</a> , Capacitive GlidePoint, pages 1 to 4, printed 05/27/04.	
	3	Analog Devices homepage, <a href="http://www.analog.com/Root/sitePage/mainSectionHome/0,2130,level4%3D%252,IMEMS">http://www.analog.com/Root/sitePage/mainSectionHome/0,2130,level4%3D%252,IMEMS</a> Accelerometers, printed 05/24/04.	
	4	BAXTER, "Capacitive Sensors", IEEE Press, pp. 29-31, (1997).	
	5	BAXTER, "Capacitive Sensors", pp. 1-17, (2000).	
	6	KOVACS, Micromachined Transducers Sourcebook, McGraw-Hill, pp. 219-221, 225-237, and 333-356 (1998).	
	7	SHIGEMATZU et al., A Single-CHIP Fingerprint Sensor and Identifier, IEEE Journal of Solid-State Circuits, Vol. 34, No. 12, pp. 1852-1859, (1999).	
	8	SUZUKI et al., A 10-24 Element High-Performance Silicon Tactile Imager, Trans. Electron Devices, Vol. 37, pp. 1852-1860 (1990).	
	9	SPANGLER et al., ISAAC-Integrated Silicon Automotive Accelerometer, Proc. Transducers '95, pp. 585-588 (1995).	
	10	WANG et al., Gas-Phase Silicon Etching with Bromine Trifluoride, Proc. Transducers '97, pp.1505- 1508 (1997).	
	11	YANG et al., Numerical Simulation of Compressible Squeezed-Film Damping, Proc. Solid-State Sensor and Actuator Workshop, pp.76-79 (1996).	
	12	YAZDI et al., Micromachined Inertial Sensors, Proc. IEEE, Vol. 86, pp. 1640-1659 (1998).	

Examiner Signature	<i>Amir Bellamy</i>	Date Considered	2/7/05
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\* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<sup>1</sup> Applicant's unique citation designation number (optional). <sup>2</sup> Applicant is to place a check mark here if English language Translation is attached.



PTO/SB/08A (08-03)

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Sheet 1	of 4	Attorney Docket Number	020859-002810US

U.S. PATENT DOCUMENTS+					
Examiner Initials*	Cite No. <sup>1</sup>	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number Kind Code <sup>2</sup> (if known)			
FB	1	US 4,814,691	03-29-1981	Garbini et al.	

FOREIGN PATENT DOCUMENTS								
Examiner Initials*	Cite No. <sup>1</sup>	Foreign Patent Document			Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T <sup>6</sup>
		Country Code <sup>3</sup>	Number <sup>4</sup>	Kind Code <sup>5</sup> (if known)				

Examiner Signature	<i>Jamuk Bellamy</i>	Date Considered	2/7/05
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